Doc No.: CN-00393 Rev.: A Release Date: 2018-03-02

RELEASE DATE: 2018-03-02		02	OWNER DEPARTMENT: Product & Tes	
		REVISIO	NHISTORY	
			(The original approval sheet is kept in DCC)	
REVISION	RELEASE DATE	AUTHOR	DESCRIPTION OF CHANGES	
A	2018-03-02	Weiwei Liu	original	

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PROCESS CHANGE NOTIFICATION

Silicon Process Change for AOTF190A60L and AOTF190A60L_001	PCN#	CN-00393A	
Dear Valued Customer,			
This letter and attached Product Change Notificati purchased within the last two years.	on (PCN) are to inf	Form you of changes to a product that you have	
As part of our continuous improvement program, we in our fab. And there will be very minor change to product quality will not be affected in any way with	to the gate pad size	-	
Please acknowledge receipt of this PCN within 30 days by signing in at http://www.aosmd.com/quality/pcn or sending the enclosed Acknowledgement Form to your local AOS Sales Representative.			
Lack of acknowledgement of the PCN within 30 da	ys constitutes accep	tance of the change.	
If you have any questions regarding this change notice, please contact your local AOS Sales Representative. http://www.aosmd.com/contact			
Sincerely,			
СК ОН			
Vice President of Quality			
Alpha and Omega Semiconductor			



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Process Change Notification

PRODUCT CATEGORY	PRODUCT(S) AFFECTED
MOSFET	AOTF190A60L and AOTF190A60L_001

TYPE OF CHANGE

Wafer processing

DESCRIPTION OF CHANGE

- a) To upgrade and add the source contact metal filling from Ti/TiN + Al to Ti/TiN + Tungsten + Al
- b) Subtle change in die layout

REASON FOR CHANGE

- a) To improve the wire bonding process window for better yield.
- b) To optimize the Rdson performance by fine-tuning gate pad size. Details see comparison table below

	From	То	
die size	4310x3410 (um)	4310x3410 (um)	
Gate pad size	508x336 (um)	480x320 (um)	

SAMPLE AVAILIBILITY

Estimated to be ready by the end of Feb 2018. (To obtain samples or production devices, please contact your AOS Sales Representative).

FIRST SHIP DATE

Estimated to be from May 31, 2018, or earlier upon customer approval.

METHOD OF IDENTIFICATION

Estimated to start from date code 18N. An accurate cut-in date code will be provided when the customer approval is received.

IMPACT OF CHANGE

Form: None
Fit: None
Function: None
Reliability: None
Environment: None

QUALIFICATION / RELIABILITY DATA:

Reliability test item	Test Condition	Sample size	Result
HTGB	T=150°C, Vgs=100%Vgsmax 1000hrs 168rs	77x3 pcs(*) 77pcs	Pass
HTRB	T=150°C, Vds=100%Vdsmax 1000hrs 168hrs	77x3 pcs(*) 77pcs	Pass

(*) Qualification data derived from generic process family.



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PCN RESPONSE:	AOS CONTACTS:
Please acknowledge receipt of this PCN within 30	Please contact your local AOS Sales Representative
days of delivery	http://www.aosmd.com/contact/
Lack of acknowledgement of the PCN within 30	
days constitutes acceptance of the change.	

QRU-00022-02(d)



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Acknowledgement of Process Change Notification

(Filled by the customer)

	· · · · · · · · · · · · · · · · · · ·		
Confirming the Receipt of the PCN			
PCN #:			
Receiving date (YY/MM/DD):			
Receiver:			
Department / Title of the receiver:			
Signature / Stamp:			
Customer Request			
Sample request	Quantity:		
Requirement of qualification data:			
Approval of the Change			
Approve	Disapprove		
Reason of disapproval:			
Approver:			
Department / Title of the approver:			
Signature / stamp:			

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Appendix: Affected Product List

Part number	Estimated sample available date	Estimated completion date of qualification	Remark
AOTF190A60L	Available	Completed	
AOTF190A60L_00	Available	Completed	

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